



SUA-110P13Cx-x-S236

SHELL : _____

鍍層厚度 :

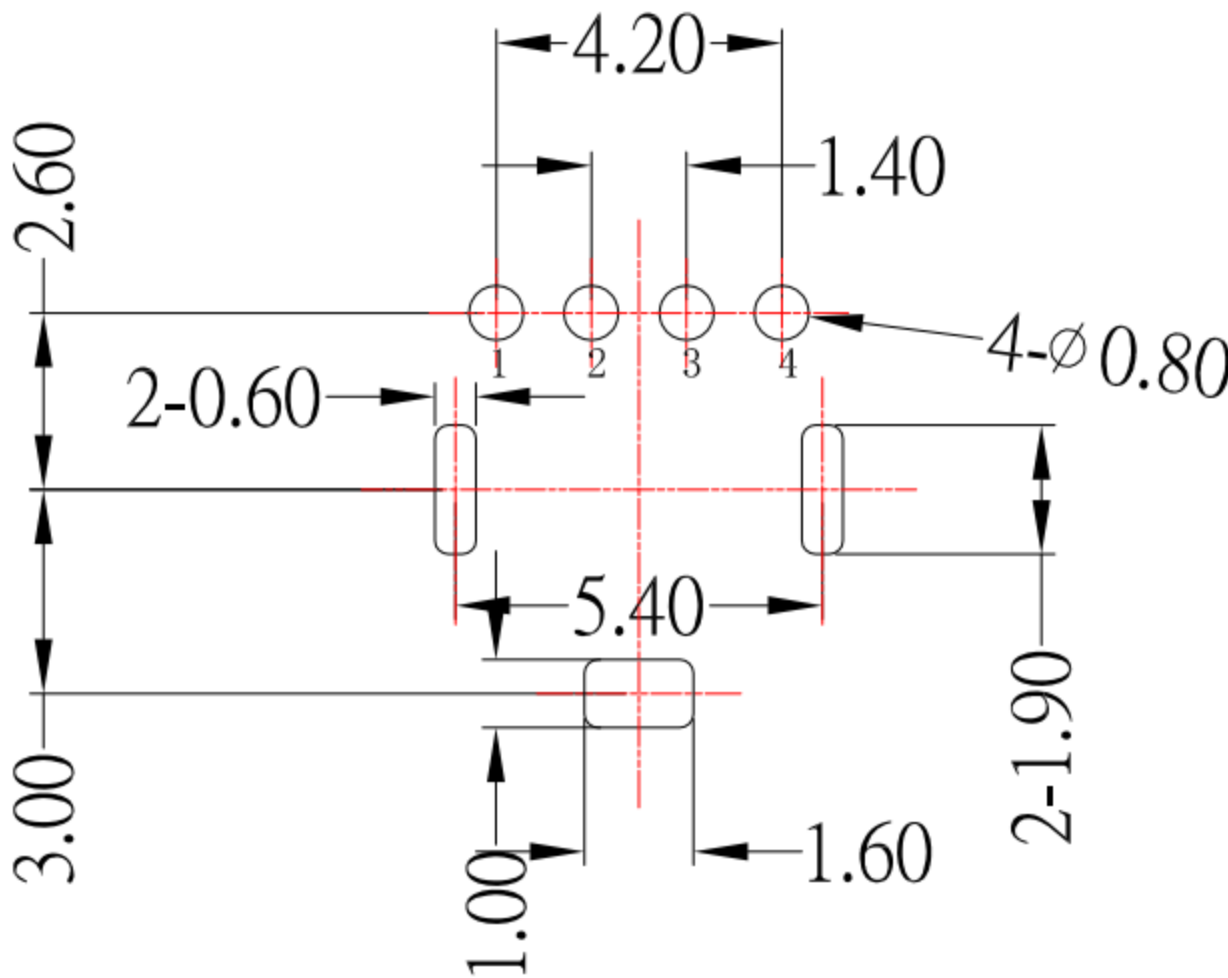
Blank : BRASS

Blank : 1u"

I : SPCC

2 : 15u"

3 : 30u"



PCB LAYOUT MOUNTING PATTERN

SPECIFICATIONS

Electrical:

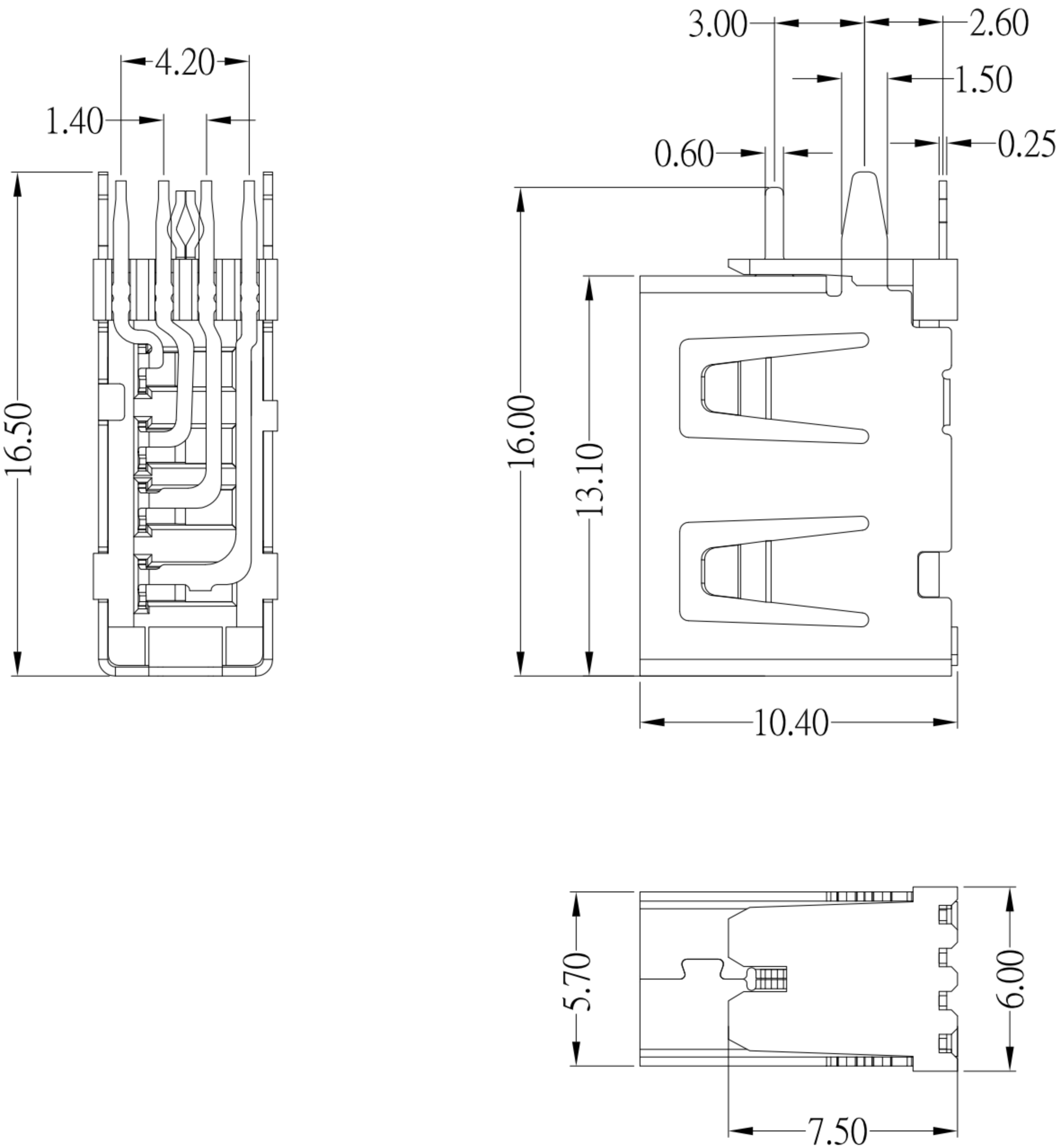
- 1.Rated Current: 2.0 A Max
- 2.Dielectric Withstanding Voltage: AC 500 V / 1MIN
- 3.Insulation Resistance: 1,000 MΩ Min
- 4.Contact Resistance: 30 mΩ Max

Material:

- 1.Housing: PBT
- 2.Contact: PhosphorBronze
- 3.Shell: Brass / Spcc

Finish:

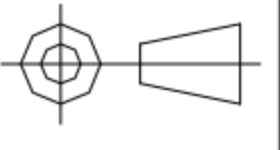
- 1.Contact: Plated Gold in Mating Area ;
Tin Plated on Solder Balls ;
Nickel under plated overall
- 2.Shell: Nickel under Plated surface layer





东莞市溪榜电子有限公司

DONG GUAN XI BANG ELECTRONICS CO., LTD

TOLERANCE UNLESS OTHERWISE STATED :	Up to 5 Above 5 ~ 15 Above 15 ~ 30 Above 30 ~ 50 Angle	±0.2 ±0.3 ±0.4 ±0.5 ±0.3°	3RD. ANGEL'S		UNITS	MM
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DRAWN BY:	DATE	MAT'L		TITLE	CONNECTOR
Jack Lu	05/12/20	FINISH		MODLE	USB AF 側插短體無捲邊 L=10.40mm
CHECKED BY:	DATE	SCALE	1 : 1	DWG NO.	SUA-110P13Cx-x-S236
Jacky Chen	05/12/20	SHEET NO.	1 of 1	PART NO.	SUA-110P13Cx-x-S236
APPROVED BY:	DATE				
Tony Kao	05/12/20				